

ON Semiconductor®

FDS4685

40V P-Channel PowerTrench® MOSFET

Features

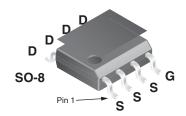
- -8.2 A, -40 V $R_{DS(ON)} = 0.027 \Omega$ @ $V_{GS} = -10 V$ $R_{DS(ON)} = 0.035 \Omega$ @ $V_{GS} = -4.5 V$
- Fast switching speed
- High performance trench technology for extremely low R_{DS(ON)}
- High power and current handling capability

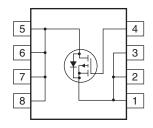
Applications

- Power management
- Load switch
- Battery protection

General Description

This P-Channel MOSFET is a rugged gate version of ON Semiconductor's advanced PowerTrench process. It has been optimized for power management applications requiring a wide range of gate drive voltage ratings (4.5V-20V).





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-40	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	-8.2	Α
	- Pulsed		-50	
P_{D}	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.4	
		(Note 1c)	1.2	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C
Thermal Ch	aracteristics		•	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	125	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	25	

Package Marking and Ordering Information

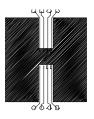
Device Marking	Device	Reel Size	Tape width	Quantity
FDS4685	FDS4685	13"	12mm	2500 units

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Charac	teristics	,	<u> </u>		•	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-40			V
ΔBV_{DSS} ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-32		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -32 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μА
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Charac	teristics (Note 2)				•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-1	-1.6	-3	V
$\Delta V_{GS(th)} \ \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		4.7		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = -10 \text{ V}, I_D = -8.2 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -7 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -8.2 \text{ A}, T_J = 125^{\circ}\text{C}$		22 29 31	27 35 42	mΩ
9FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_D = -8.2 \text{ A}$		22		S
Dynamic C	haracteristics				•	
C _{iss}	Input Capacitance	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1872		pF
C _{oss}	Output Capacitance			256		pF
C _{rss}	Reverse Transfer Capacitance			134		pF
R _G	Gate Resistance	V _{GS} = 15 mV, f = 1MHz		4		Ω
Switching	Characteristics (Note 2)				•	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -20 \text{ V}, I_D = -1 \text{ A},$		14	25	ns
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$		11	20	ns
t _{d(off)}	Turn-Off Delay Time			50	80	ns
t _f	Turn-Off Fall Time			18	32	ns
Q _g	Total Gate Charge	$V_{DS} = -20 \text{ V}, I_D = -8.2 \text{ A},$		19	27	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -5 \text{ V}$		5.6		nC
Q _{gd}	Gate-Drain Charge			6.1		nC
Drain-Sou	rce Diode Characteristics		•	•	•	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -2.1 A (Note 2)		-0.7	-1.2	V
t _{rr}	Diode Reverse Recovery Time	I _F = -8.2 A,		26		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$		15		nC

Notes:

1. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a) 50°C/W when mounted on a 1 in² pad of 2 oz



b) 105°/W when mounted on a .04 in² pad of 2 oz copper



c) 125°/W when mounted on a minimum pad.



Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300 μ s, Duty Cycle < 2.0%

Typical Characteristics:

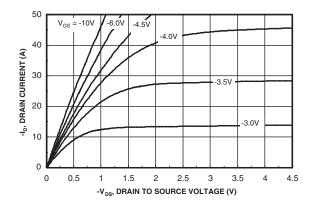


Figure 1. On-Region Characteristics.

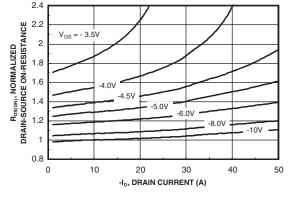


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

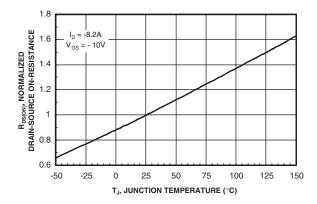


Figure 3. On-Resistance Variation with Temperature.

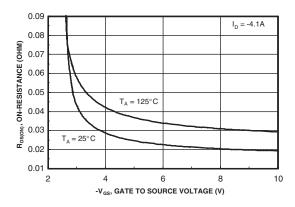


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

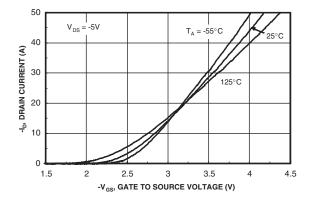


Figure 5. Transfer Characteristics.

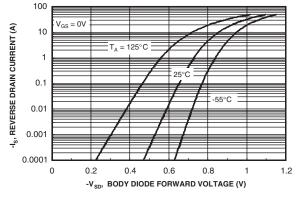
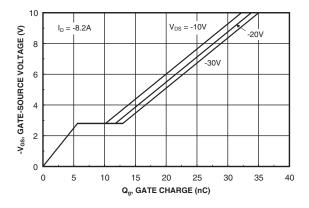


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics:



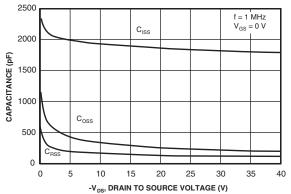
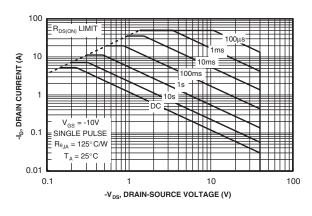


Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.



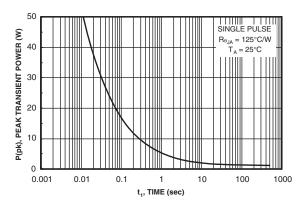


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

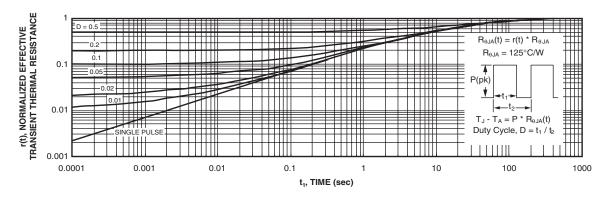


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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